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SUPPLEMENTAL EXAMINER'S AMENDMENT

An examiner's amendment to the record appears below. Should the changes and/or
additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR.
 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the
payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with John W. Bailey (Reg. No. 32,881) on August 12, 2010.

The application has been amended as follows:

In the claims:

9. (Currently Amended) An epoxy resin composition comprising 100 parts by mass of an epoxy resin and 0.1 to 100 parts by mass of an amine hardener, which is selected from the group consisting of:

an amine hardener (C), a microcapsule type hardener (D), and a master batch type hardener (F);

wherein the amine hardener (C) comprises: an amine adduct (A) and a low molecular weight amine compound (B) as major components; wherein the amine adduct (A) is obtained by a reaction between an epoxy resin (a1) and an amine compound (b1) and has a molecular weight distribution, which is defined by the ratio of the weight average molecular weight and the number average molecular weight, of 3 or lower, and wherein the content of the low molecular weight amine compound (B) is 0.001 to 1 part by mass, based on 100 parts by mass of the amine adduct (A);

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wherein the microcapsule type hardener (D) comprises: a core and a shell; wherein said core comprises the amine hardener (C); and wherein said shell contains a synthetic resin or an inorganic oxide; and

wherein the master batch type hardener (F) comprises: a hardener selected from the amine hardener (C) and the microcapsule type hardener (D), an epoxy resin (E), and a highly soluble epoxy resin (G); wherein the highly soluble epoxy resin (G): has a solubility parameter of 8.900 to 12.00; has a molecular weight between crosslinked points after hardening of 105 to 150; and is contained in an amount of not lower than 0.1% by weight, based on the epoxy resin (E); and wherein the total chlorine amount of said master batch type hardener (F) is not higher than 2000 ppm.

20. (Currently Amended) A mater batch type hardener (F) for an epoxy resin comprising: the amine hardener (C) according to claim 1, an epoxy resin (E), and a highly soluble epoxy resin (G);

wherein the highly soluble epoxy resin (G): has a solubility parameter of 8.900 to 12.00; has a molecular weight between crosslinked points after hardening of 105 to 150; and is contained in an amount of not lower than 0.1% by weight, based on the epoxy resin (E); and wherein the total chlorine amount of said master batch type hardener (F) for an epoxy resin is not higher than 2000 ppm.

Communication

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michael J. Feely whose telephone number is (571)272-1086. The examiner can normally be reached on M-F 8:30 to 5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Harold Y. Pyon can be reached on 571-272-1498. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Michael J Feely/ Primary Examiner, Art Unit 1796

August 12, 2010